

**Thin film soldered RSAM on W/Cu submount, glued with silver epoxy on a water cooled copper heat sink with 25.0 mm diameter for high power applications**

**RSAM- $\lambda$ - 25.0h**

SAM chip area	standard:	4mm x 4mm
Chip thickness	standard:	400 $\mu$ m
Front side	the RSAM is protected with a dielectric front layer	

The RSAM chip is thin film soldered on a gold plated W/Cu submount using a Au/Sn solder.

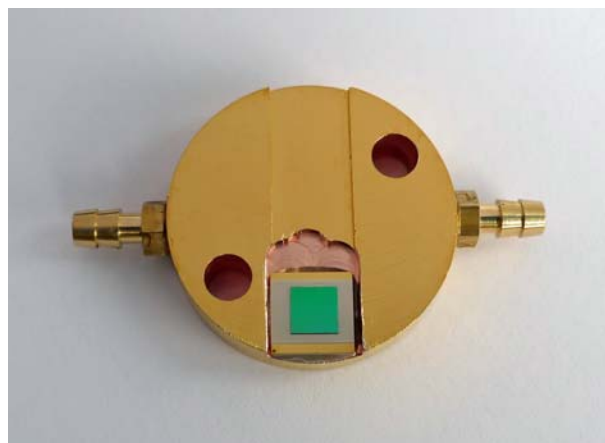
Submount dimensions: 7mm x 7mm x 1mm

Submount material: W/Cu 90 / 10

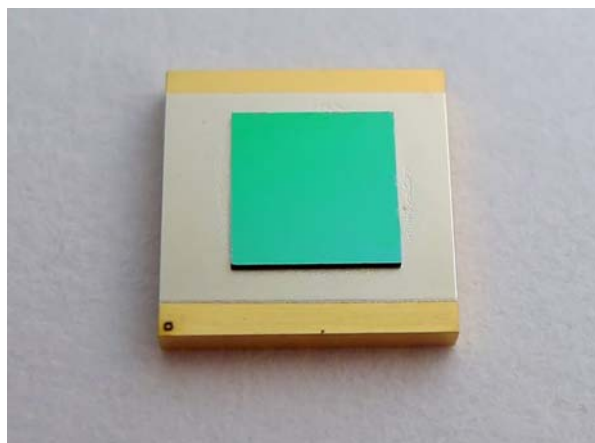
The W/Cu submount is glued using a silver containing epoxy on a water cooled copper heat sink with 25.0 mm diameter. This heat sink combination ensures a low temperature of the absorber layer in case of high dissipated power  $\geq 1$  W.

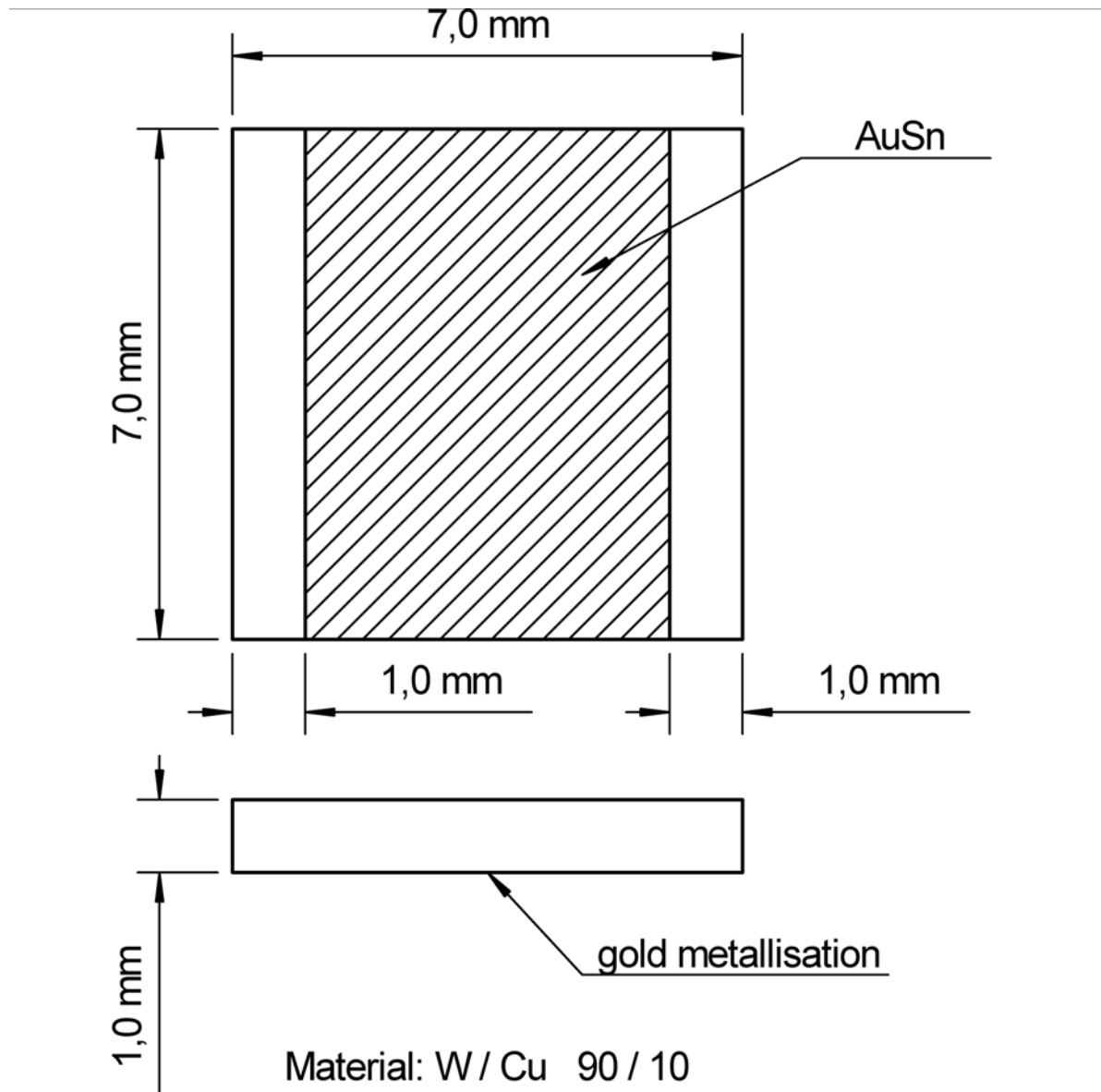
- The **standard** position of the SAM is at the center of the water cooled heat sink.
- **Optional** the SAM can be mounted on the edge of the water cooled heat sink without extra charges.

Edge mounted RSAM



RSAM on W/Cu submount



**Cu/W submount**

### Water cooled copper heat sink

The water cooled copper heat sink comes with two 1 m long tubes for water supply. The inner diameter of the tube is 3 mm and the outer diameter is 5 mm. The water tube connectors are not shown in the sketch below.

